

Title (en)

SHAPE PROCESSES, FEEDSTOCK MATERIALS, CONDUCTIVE MATERIALS, AND/OR ASSEMBLIES

Title (de)

FORMVERFAHREN, EINSATZSTOFFE, LEITFÄHIGE MATERIALIEN UND/ODER ANORDNUNGEN

Title (fr)

PROCÉDÉS SHAPE, MATÉRIAUX DE CHARGE D'ALIMENTATION, MATÉRIAUX CONDUCTEURS ET/OU ENSEMBLES

Publication

**EP 4034316 A1 20220803 (EN)**

Application

**EP 20869757 A 20200928**

Priority

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- US 2020053168 W 20200928

Abstract (en)

[origin: WO2021062415A1] Shear-assisted extrusion processes for forming extrusions of a desired composition from a feedstock material are provided. The processes can include applying a rotational shearing force and an axial extrusion to the same location on the feedstock material. Devices for this can include a die tool defined by a die face extending from a rim of the die face inwardly at an angle greater than zero in relation to a sidewall of the die tool in at least one cross section; and/or a die tool defining an opening configured to receive feedstock material for extrusion and further defining a die face defining a recess within the die face and contiguous with the opening. Shear-assisted extrusion processes are also provided that can mix different portions of the feedstock material within a recess about the opening prior to feedstock material entering the opening; and extruding the mixed portions.

IPC 8 full level

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CPC (source: EP)

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